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application 07/765,928 in turn was a continuation-in-part of United States Patent Application 07/673,020, filed March 21, 1991, now United States Patent 5,148,265 and said Application 07/765,928 was a continuation-in-part of United States Patent Application 07/586,758, filed September 24, 1990, now United States Patent 5,148,266. Said United States Patent Application 08/030,194 is also a continuation-in-part of said Applications 07/586,758 and 07/673,020. *filed 7/24/91 now 5,148,266* *filed 3/21/91, now 5,148,265*

Page 1, line 3, before "TECHNICAL FIELD" insert -- Cross Reference To Related

03
Applications --;

line 9, delete "TECHNICAL FIELD" and insert -- Background Of The Invention --.

Page 6, line 9, change "sulder" to -- solder --.

Page 12, line 24, change "thermolcompression" to -- thermocompression --.

Page 33, line 23, change "centerto-center" to -- center-to-center --.

In the Abstract:

Please cancel the abstract presently on file and substitute therefore the following: -- Abstract Of The Disclosure

04
A semiconductor chip having contacts on the central region of its top surface is provided with a dielectric element overlying the central portion of the top surface. The dielectric element has a first surface facing toward the chip and a second surface facing away from the chip, a hole encompassing the central contacts and an edge bounding the hole. Central contact leads extend from the central contacts on the chip to central terminals on the dielectric element. The terminals on the dielectric element may be connected to a substrate using techniques commonly employed in surface mounting of electrical devices, such as solder bonding. The leads, and